

Abstract

A solder ball assembly for use in the formation of solder bumps on electrodes of a substrate for electronic components includes a heat-resisting sheet having a plurality of holes formed therein. Each hole has a solder ball disposed therein. The sheet includes an adherent layer exposed to the interior of each hole on the wall and/or bottom of the hole such that the adherent layer contacts and holds the solder balls in the holes. Solder bumps are formed by positioning the assembly on a substrate such that the solder balls held in the holes come into contact with the electrodes of the substrate. The assembly and the substrate are heated together to melt the solder balls in the holes. After solidification of the solder, the heat-resisting sheet of the assembly is removed from the substrate, leaving a solder bump on each electrode.